1/21/04



Tab settings ⇔⇔ ⇔ ▼	▼	<b>V</b>	<b>Y Y Y</b>
To the Honorable Commissioner of Pate	ents and Trademarks: I	Please record the attache	d original documents or copy thereof.
Name of conveying party(ies):		2. Name and addre	ess of receiving party(ies)
National City Bank		Name: Brush In	ternational, Inc.
		Internal Address	·
		mornar / darese	·
Additional name(s) of conveying party(ies) attache	ed? Yes VNo		**************************************
3. Nature of conveyance:	•		
Assignment Me	erger		
Security Agreement Cr	hange of Name	Street Address:	17876 St. Clair Avenue
Other_Release of Security Interes	•		
Outer		OlI	٠
12/04/03 Execution Date:		City: Clevelan	d State: OH Zip: 44110
		Additional name(s) 8	address(es) attached? 🗸 Yes
4. Application number(s) or patent numb	per(s):		
If this document is being filed together	r with a new applic	cation, the execution	date of the application is:
A. Patent Application No.(s) (See So	chedule A)	B. Patent No.(s)	(See Schedule A)
~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~			
A	 Additional numbers atta	ached? 🗸 Yes No	
5. Name and address of party to whom o	correspondence		
5. Name and address of party to whom concerning document should be maile	correspondence	6. Total number of a	pplications and patents involve
5. Name and address of party to whom o concerning document should be maile Name: Robert H. Earp, III	correspondence ed:	6. Total number of a	pplications and patents involved a 3.41)
5. Name and address of party to whom concerning document should be maile  Name: Robert H. Earp, III	correspondence	6. Total number of a 7. Total fee (37 CFF	pplications and patents involve  3.41)
5. Name and address of party to whom o concerning document should be maile Name: Robert H. Earp, III	correspondence	6. Total number of a 7. Total fee (37 CFF  Enclosed (1)	pplications and patents involved 3.41)
5. Name and address of party to whom concerning document should be maile  Name: Robert H. Earp, III	correspondence	6. Total number of a 7. Total fee (37 CFF  Enclosed (1)	pplications and patents involved 3.41)
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5. Name and address of party to whom concerning document should be maile  Name: Robert H. Earp, III	correspondence ed: (INS, CO., LPA	6. Total number of a 7. Total fee (37 CFF  Enclosed (1)  Authorized to  8. Deposit account	pplications and patents involved 3.41)
5. Name and address of party to whom of concerning document should be maile Name: Robert H. Earp, III  MCDONALD HOPK Internal Address:	correspondence ed: CINS, CO., LPA	6. Total number of a 7. Total fee (37 CFF  Enclosed (37 CFF  Authorized to	pplications and patents involved 3.41)
5. Name and address of party to whom of concerning document should be maile Name:  Robert H. Earp, III  MCDONALD HOPK Internal Address:  Street Address:  2100 BANK ONE CE	correspondence ed:  KINS, CO., LPA	6. Total number of a 7. Total fee (37 CFF  Enclosed (1)  Authorized to  8. Deposit account	pplications and patents involved 3.41)
5. Name and address of party to whom of concerning document should be maile Name: Robert H. Earp, III  MCDONALD HOPK Internal Address: 2100 BANK ONE CE	correspondence ed:  KINS, CO., LPA	6. Total number of a 7. Total fee (37 CFF  Enclosed (1)  Authorized to  8. Deposit account	pplications and patents involved 3.41)
5. Name and address of party to whom of concerning document should be maile Name:  Robert H. Earp, III  MCDONALD HOPK Internal Address:  Street Address:  2100 BANK ONE CE	correspondence ed:  KINS, CO., LPA	6. Total number of a 7. Total fee (37 CFF  Enclosed (15  Authorized to 8. Deposit account 13-0265	pplications and patents involved 3.41)
5. Name and address of party to whom of concerning document should be maile Name:  Robert H. Earp, III  MCDONALD HOPK Internal Address:  Street Address:  2100 BANK ONE CE	CORRESPONDENCE ENTER	6. Total number of a 7. Total fee (37 CFF  Enclosed (15  Authorized to 8. Deposit account 13-0265	pplications and patents involved 3.41)
5. Name and address of party to whom concerning document should be maile Name: Robert H. Earp, III  MCDONALD HOPK Internal Address: MCDONALD HOPK Street Address: 2100 BANK ONE CE 600 SUPERIOR AVE., E.  City: CLEVELAND State: OH Zip: 44	CORRESPONDENCE ENTER	6. Total number of a 7. Total fee (37 CFF  Enclosed (15  Authorized to 8. Deposit account 13-0265	pplications and patents involved 3.41)
5. Name and address of party to whom concerning document should be maile Name: Robert H. Earp, III  MCDONALD HOPK Internal Address: MCDONALD HOPK Street Address: 2100 BANK ONE CE 600 SUPERIOR AVE., E.  City: CLEVELAND State: OH Zip: 44	CORRESPONDENCE ENTER	6. Total number of a 7. Total fee (37 CFF  Enclosed (15  Authorized to 8. Deposit account 13-0265	pplications and patents involved 3.41)
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**PATENT** 

**REEL: 014892 FRAME: 0838** 

Williams Advanced Materials, Inc. 2978 Main Street Buffalo, NY 12414-1099

Circuits Processing Technology, Inc. 1817 Peacock Boulevard Oceanside, California 92054

Technical Materials, Inc. 11103 Foxbrook Ct. Louisville, KY 40223

Brush Resources, Inc. 10 Miles North Highway 6 Delta, Utah 84624

Brush Ceramic Products, Inc. 6100 South Tucson Boulevard Tucson, Arizona 85706

Zentrix Technologies, Inc. 6100 S. Tucson Boulevard Tucson, Arizona 85706-4520

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PATENT REEL: 014892 FRAME: 0839

## SCHEDULE A PATENTS

TITLE	PATENT NO.	ISSUE DATE
PROCESS FOR MAKING IMPROVED COPPER/TUNGSTEN COMPOSITES	5686676	Nov. 11, 1997
PROCESS FOR RETARDING SPONTANEOUS COMBUSTION OF POWDERY MIXTURES	5826159	Oct. 20, 1998
SEMICONDUCTOR PACKAGE HAVING A EUTECTIC BONDING LAYER	5760473	June 2, 1998
METHOD FOR BONDING A CERAMIC TO A METAL WITH A COPPER-CONTAINING SHIM	6056186	May 2, 2000
METHOD FOR CREATING A HERMETIC SEAL AND PACKAGE MADE THEREBY	6153449	Nov. 28, 2000
FUNCTIONALLY GRADED METAL SUBSTRATES AND PROCESS FOR MAKING SAME	6114048	Sept. 5, 2000
BERYLLIUM-CONTAINING ALLOYS OF MAGNESIUM	5413644	May 9, 1995
SEMI-SOLID PROCESSING OF BERYLLIUM- CONTAINING ALLOYS OF MAGNESIUM	5679182	Oct. 21, 1997
MAGNESIUM-BERYLLIUM DISK DRIVE ARMSET	5475549	Dec. 12, 1995
ALUMINUM ALLOYS CONTAINING BERYLLIUM AND INVESTMENT CASTING OF SUCH ALLOYS	6042658	March 28, 2000
COMPOSITE DISK DRIVE ARMSET	6057989	May 2, 2000
PROCESS FOR CLADDING PRECIOUS METALS TO PRECIPITATION HARDENABLE MATERIALS	5370753	Dec. 6, 1994
BERYLLIUM-BERYLLIUM OXIDE COMPOSITES	5304426	April 19, 1994
PRODUCTION OF BERYLLIUM OXIDE POWDERS WITH CONTROLLED MORPHOLOGY AND QUALITY	5268334	Dec. 7, 1993
METHOD OF MAKING BERYLLIUM-BERYLLIUM OXIDE COMPOSITES	5124119	June 23, 1992
PROCESSING OF COPPER ALLOYS AND PRODUCT	4724013	Feb. 9, 1998
PROCESSING OF COPPER ALLOYS	4599120	July 8, 1986
HEAT EXCHANGER ASSEMBLY AND METHOD FOR MAKING THE SAME	5777259	July 7, 1998
BERYLLIUM-CONTAINING ALLOYS OF ALUMINUM AND SEMI-SOLID PROCESSING OF SUCH ALLOYS	5716467	Feb. 10, 1998

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PATENT REEL: 014892 FRAME: 0840

TITLE	PATENT NO.	ISSUE DATE
ALUMINUM ALLOYS CONTAINING BERYLLIUM	5667600	Sept. 16, 1997
AND INVESTMENT CASTING OF SUCH ALLOYS		
ALUMINUM ALLOYS CONTAINING BERYLLIUM	5642773	July 1, 1997
AND INVESTMENT CASTING OF SUCH ALLOYS		
BERYLLIUM-CONTAINING ALLOYS OF	5551997	Sept. 3, 1997
ALUMINUM AND SEMI-SOLID PROCESSING OF		
SUCH ALLOYS		
MULTILAYER METAL LEADFRAME	5525836	June 11, 1996
METHOD FOR MAKING A MULTILAYER METAL	5437096	Aug. 1, 1995
LEADFRAME		
BONDING BERYLLIUM TO COPPER ALLOYS	5901336	May 4, 1999
USING POWDER METALLURGY COMPOSITIONAL		
GRADIENTS		
METHOD OF MAKING MULTILAYER SYSTEM	5761799	June 9, 1998
ALTERNATE ELECTROLYTIC/ELECTROLESS-	4842961	June 27, 1989
LAYERED LID FOR ELECTRONICS PACKAGE		
MULTILAYER LAMINATE PRODUCT AND	5686190	Nov. 11, 1997
PROCESS		
MULTILAYER LAMINATE PRODUCT AND	5525753	June 11, 1996
PROCESS		
MULTILAYER LAMINATE PROCESS	6022426	Feb. 8, 2000
MULTILAYER METAL COMPOSITE FOR	5783317	July 21, 1998
MICROWAVE TUBING AND THE LIKE		1 2 2 3 2 3 2 3 2 3 2 3 2 3 2 3 2 3 2 3
PROCESS FOR MAKING IMPROVED	5686676	Nov. 11, 1997
COPPER/TUNGSTEN COMPOSITES		, , , , , , ,
PROCESS FOR MAKING IMPROVED NET SHAPE	5993731	Nov. 30, 1999
OR NEAR NET SHAPE METAL PARTS		
NICKEL CLAD CORROSION RESISTANT LID FOR	4737418	April 12, 1988
SEMICONDUCTOR PACKAGE		
	App. No.	
CARRIER SUB-ASSEMBLY WITH INSERTS AND	I ADD. INO.	i

COI-1257949v1 -3-

## RELEASE OF SECURITY INTEREST

This Release is executed by National City Bank as of the date set forth below.

WHEREAS, on September 28, 2001, National City Bank, a national banking association, Brush International, Inc., an Ohio corporation ("BII"), Williams Advanced Materials Inc., a New York corporation ("WAM"), Circuits Processing Technology, Inc., a California corporation ("CPI"), Technical Materials, Inc., an Ohio corporation ("TMI"), Brush Resources Inc., a Utah corporation ("BRI"), Brush Ceramic Products Inc., an Arizona corporation ("BCP"), and Zentrix Technologies Inc., an Arizona corporation ("ZTI" and, collectively with WAM, CTP, TMI, BII, BRI and BCP "Brush") entered into a Subsidiary Security Agreement, as later amended, granting to National City Bank a security interest in, among other items, the patents and patent applications listed on Schedule A attached hereto as well as future patents and patent applications (the "Patents");

WHEREAS, on May 15, 2002, National City Bank caused the lien created in the Subsidiary Security Agreement to be recorded against the Patents in the U.S. Patent and Trademark Office on Reel 012896 at Frame 0249; and

WHEREAS, Brush has satisfied all outstanding Secured Obligations (as defined in the Subsidiary Security Agreement);

NOW THEREFORE, for and in consideration of Brush's satisfaction of all outstanding Secured Obligations, National City Bank hereby releases all liens, lien rights, security interests, claims or demands of any kind whatsoever, which National City Bank now has or might have against the Patents pursuant to the Subsidiary Security Agreement

Date: Danley 4, 1003	Que I. Il
(	_

By: Dale F. Klose
Senior Vice President

Title:\_\_\_\_

STATE OF Olivo COUNTY OF Cuyahoga

This instrument was acknowledged before me on December 1, 2003, by Dale F. Klose, Sonion Vice President of National City Bank

Notary Public

SANDRA J. SLUSARCZYK NOTARY PUBLIC - STATE OF CHID Recorded in Constructs County My Comm. Expires Dec. 1 2004

COI-1257949v1

RECORDED: 01/21/2004

PATENT REEL: 014892 FRAME: 0842